

- B1
- at least one placement head on said Y-slide, which placement head is drivable in a Y-direction, characterized in that the Y-slide is provided with at least two placement heads which can be independently driven in a Y-direction.
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3. (Amended) A method of placing components on a printed circuit board by means of a component placement machine comprising:

- B2
- in a first period of time, moving a first placement head to a desired X-Y position above a first feeder and, subsequently, picking up a component from the first feeder, moving a second placement head along a Y-slide to a desired Y-position so as to prepare for the placement of a previously picked-up component on the printed circuit board,
 - in a second period of time following the first period of time, moving the second placement head to a desired X-Y position above the printed circuit board and, subsequently, placing the component on the printed circuit board,
 - in a third period of time following the second period of time, moving the second placement head to a desired X-Y position above a second feeder and, subsequently, picking up a component from the second feeder, moving the first placement head along the Y-slide to a desired Y-position so as to prepare for the placement on the printed circuit board of the component picked up in the first period of time, and

- in a fourth period of time following the third period of time, moving the first placement head to a desired X-Y position above the printed circuit board and, subsequently, placing the component on the printed circuit board.

4. (Amended) A method of placing components on a printed circuit board by means of a component placement machine comprising:

- B2
- in a first period of time, moving a first series of placement heads to a desired X-Y position above a first feeder and, subsequently, simultaneously picking up components from the first feeder, moving a second series of placement heads along one of a multitude of Y-slides to a desired Y-position so as to prepare for the placement on the printed circuit board of previously picked-up components,
 - in a second period of time following the first period of time, moving the second series of placement heads to a desired X-Y position above the printed circuit board and, subsequently, placing the components simultaneously on the printed circuit board,
 - in a third period of time following the second period of time, moving the second series of placement heads to a desired X-Y position above a second feeder and, subsequently, simultaneously picking up components from the second feeder, moving the first series of placement heads moves along the one of a multitude of